

EP466FO HIGH TEMPERATURE EPOXY ADHESIVE

● PRODUCT DESCRIPTION

EP466FO is a 2K epoxy adhesive system which resists high temperature up to 200°C. Product is designed for semiconductor, hybrid, fiber optic and medical applications. EP466FO has good bonding properties to metals and many plastics. Complies (pending) with ISO 10993-5 medical grade requirements. Resistant to sterilization methods like EtO, gamma and autoclave.

● CURING PROPERTIES

Pot Life	80°C	100°C	120°C	150°C
3 hours	30 min.	10 min.	5 min.	1 min.

● UNCURED PROPERTIES

Base	Epoxy
Color	Reddish Amber
Mixing Ratio (by weight)	10:1
Viscosity (mixed)	3000 - 5000 cPs
Density	1,17

● CURED PROPERTIES

Hardness Shore D	80 - 90
Temperature Resistance	-55°C + 240°C
Shrinkage	<1%
Glass Transition Temperature	> 90°C
Lap Shear	14N/mm ²
E-modul (MPa)	3500

● INSTRUCTIONS FOR USE

All surfaces must be clean and dry. Mix thoroughly until uniform color is achieved. Apply adhesive to substrate and cure per suitable time and temperature listed in curing properties. Do not mix more than 20 grams.

